

EAST - [0325586.wsp.1]

File View Edit Tools Window Help

☐ Drafts ☒ Pending ☒ Active ☐ Failed ☐ Saved ☐ Favorites ☒ Tagged (0)

L1: (554567) (base flexible bend tape shaped tab interconnect carrier film) with substrate
L2: (122121) reel
L3: (128331) 2 reeling reeled
L4: (54686) (interconnect wiring tracing) with pattern
L5: (74510) (interconnect lead leadframe wiring tracing) with pattern
L6: (254) 1 and 3 and 5
L7: (42163) (base flexible bend tape shaped tab interconnect carrier film substrate) and 4
L8: (35324) (base flexible bend tape shaped tab interconnect carrier film substrate) same 4
L9: (44716) (base flexible bend tape shaped tab interconnect carrier film substrate) same 5
L10: (112) 3 same 3
L11: (76) 10 not 6

(0) base flexible bend tape shaped tab interconnect carrier film substrate

(96375) (bendable flexible moveable) with (frame container supporter)
(1803) (chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (f...
(51221) (bendable flexible moveable) with (frame)
(1235) ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (...
(432) ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (...
(432) (((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with...
(96375) (bendable flexible moveable) with (frame container supporter)
(1803) (bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic...
(1235) ((bendable flexible moveable) with (frame container supporter)) and ((chip die dice i...
(432) (((bendable flexible moveable) with (frame container supporter)) and ((chip die dice i...

10 not 6

	U	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	2	3
1	<input type="checkbox"/>	US 20020044383 A1	20020418	30	Magnetic tape cassette	360/132			Ashikawa, Teruo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	US 20010053319 A1	20011220	7	Progressively-formed clinch nut	411/437			Swanstrom, Kenneth A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	US 6216342 B1	20010417	41	Method for fabricating a matrix switchboard and	29/852	29/846; 474/254		Hosogai, Masao et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	US 5986309 A	19990323	41	Matrix switch board, connection pin, and method	200/1R	200/175; 439/48		Hosogai, Masao et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	US R835950 E	19981110	24	Recording medium cassette and a recording/reproducing	242/344			Sawada, Takashi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	US 5808355 A	19980915	9	Lead frame of a semiconductor device and a	257/666	257/669; 257/670		Kim, Yong-yeon et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	US 5833528 A	19970527	11	Lead frame structure for IC devices with strengthened	257/666	257/672; 257/676		Abbott, Donald C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	US 5810437 A	19970311	9	Lead frame for integrated circuits	257/670	257/666; 257/675		Fréchette, Raymond A.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	US 5592734 A	19970114	33	Method and apparatus for forming a film mounted	29/827	29/564.3; 29/564.4;		Houghton, Jon C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	US 5502395 A	19960326	6	Semiconductor device burn-in apparatus	324/750	324/419; 324/537		Wada, Shinobu	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11	<input type="checkbox"/>	US 5448877 A	19950912	11	Method for packing lead frames for shipment thereof	53/471	53/472; 53/475		Chu, Hsiang	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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Details HTML